

Abstract**Process for producing semiconductor wafers**

A process for producing semiconductor wafers, wherein a single-crystal ingot of semiconductor material is pulled and at least one wafer is removed from the ingot of semiconductor material, wherein the wafer is subjected to a thermal treatment comprising a heat treatment step in which a radial temperature gradient acts on the wafer, wherein an analysis of the wafer of semiconductor material in respect of the formation of defects in the crystal lattice, so-called stress fields, is carried out.

Drawing relating to Abstract: fig. 1